

# L293, L293D QUADRUPLE HALF-H DRIVERS

SLRS008C – SEPTEMBER 1986 – REVISED NOVEMBER 2004

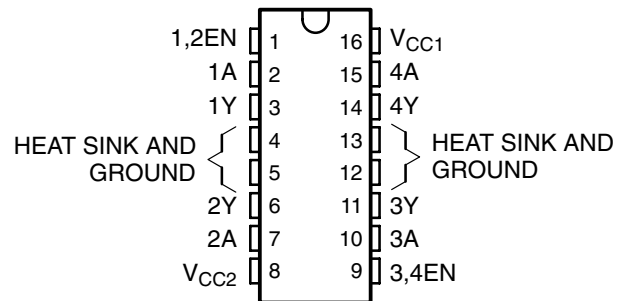
- Featuring Unitrode L293 and L293D Products Now From Texas Instruments
- Wide Supply-Voltage Range: 4.5 V to 36 V
- Separate Input-Logic Supply
- Internal ESD Protection
- Thermal Shutdown
- High-Noise-Immunity Inputs
- Functionally Similar to SGS L293 and SGS L293D
- Output Current 1 A Per Channel (600 mA for L293D)
- Peak Output Current 2 A Per Channel (1.2 A for L293D)
- Output Clamp Diodes for Inductive Transient Suppression (L293D)

## description/ordering information

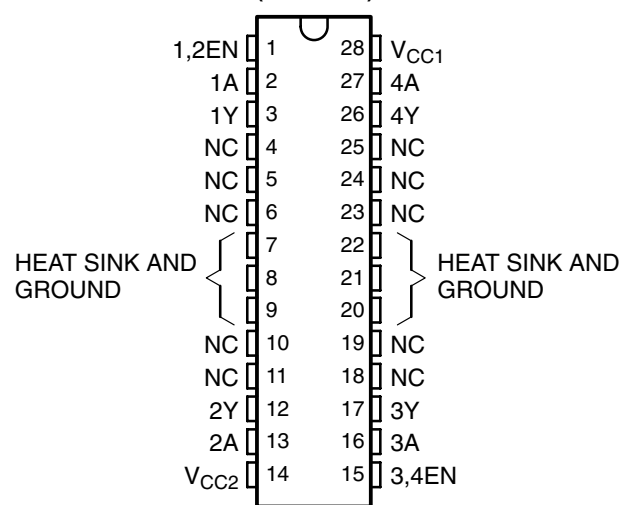
The L293 and L293D are quadruple high-current half-H drivers. The L293 is designed to provide bidirectional drive currents of up to 1 A at voltages from 4.5 V to 36 V. The L293D is designed to provide bidirectional drive currents of up to 600-mA at voltages from 4.5 V to 36 V. Both devices are designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.

All inputs are TTL compatible. Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled, and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled, and their outputs are off and in the high-impedance state. With the proper data inputs, each pair of drivers forms a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

L293 . . . N OR NE PACKAGE  
L293D . . . NE PACKAGE  
(TOP VIEW)



L293 . . . DWP PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	HSOP (DWP)	Tube of 20	L293DWP	L293DWP
	PDIP (N)	Tube of 25	L293N	L293N
	PDIP (NE)	Tube of 25	L293NE	L293NE
		Tube of 25	L293DNE	L293DNE

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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**TEXAS  
INSTRUMENTS**

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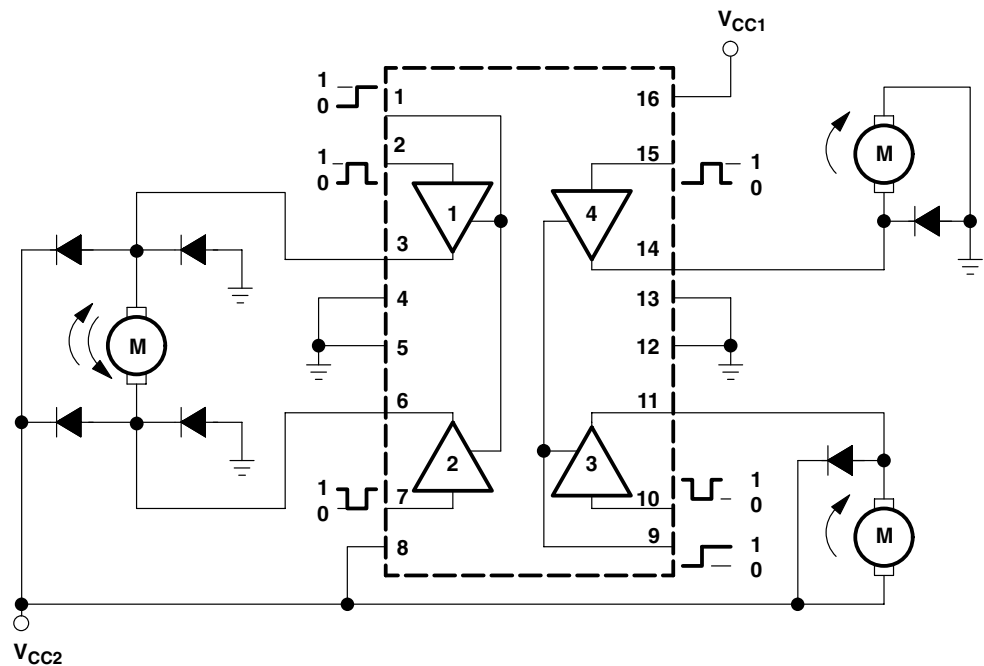
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description/ordering information (continued)

On the L293, external high-speed output clamp diodes should be used for inductive transient suppression. A  $V_{CC1}$  terminal, separate from  $V_{CC2}$ , is provided for the logic inputs to minimize device power dissipation. The L293 and L293D are characterized for operation from 0°C to 70°C.

block diagram



NOTE: Output diodes are internal in L293D.

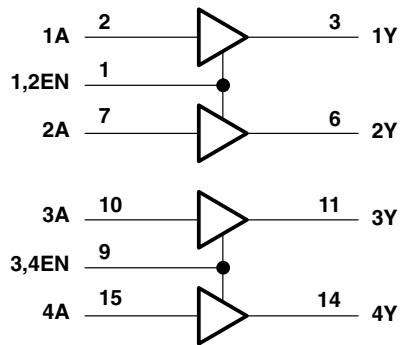
FUNCTION TABLE  
(each driver)

INPUTS†		OUTPUT Y
A	EN	
H	H	H
L	H	L
X	L	Z

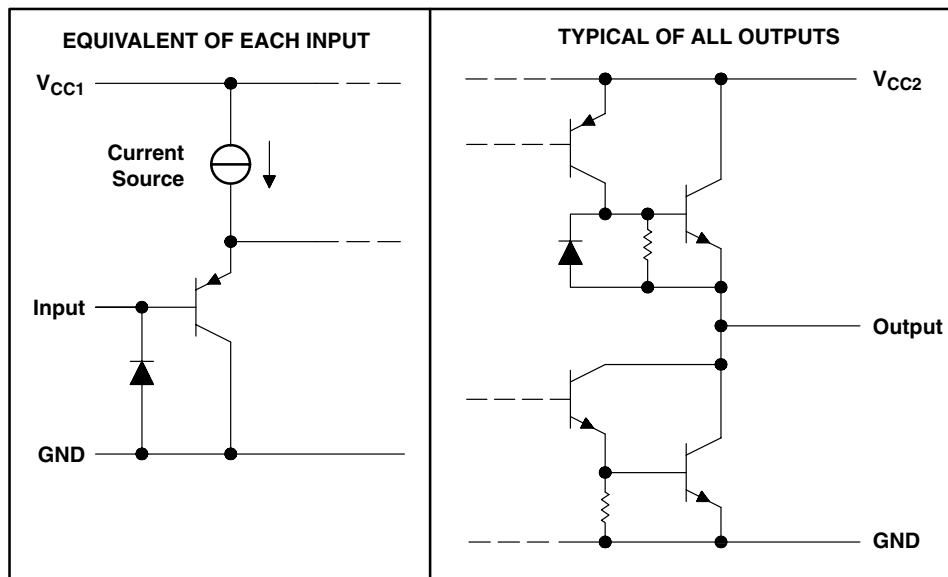
H = high level, L = low level, X = irrelevant,  
Z = high impedance (off)

† In the thermal shutdown mode, the output is  
in the high-impedance state, regardless of  
the input levels.

**logic diagram**



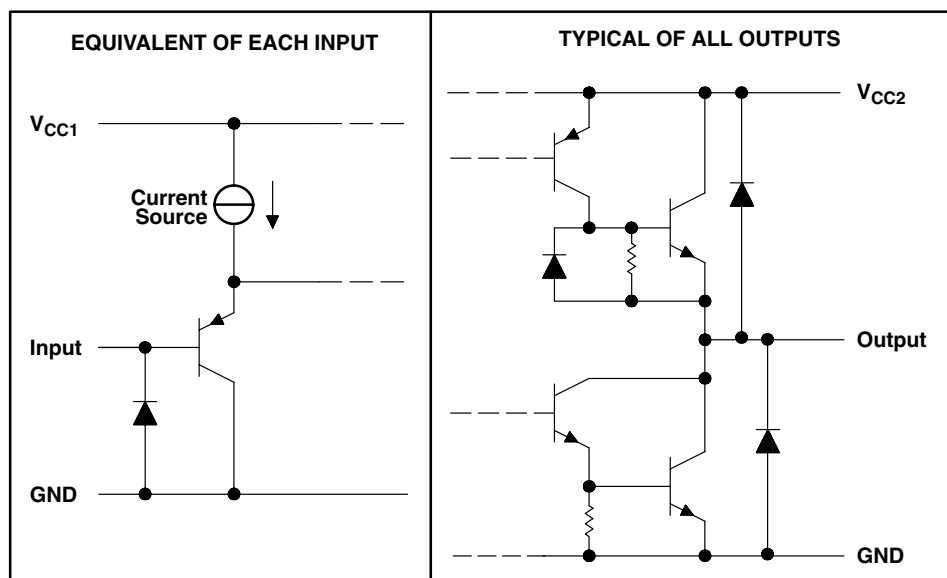
**schematics of inputs and outputs (L293)**



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## schematics of inputs and outputs (L293D)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC1}$ (see Note 1)	36 V
Output supply voltage, $V_{CC2}$	36 V
Input voltage, $V_I$	7 V
Output voltage range, $V_O$	-3 V to $V_{CC2} + 3$ V
Peak output current, $I_O$ (nonrepetitive, $t \leq 5$ ms): L293	$\pm 2$ A
Peak output current, $I_O$ (nonrepetitive, $t \leq 100$ $\mu$ s): L293D	$\pm 1.2$ A
Continuous output current, $I_O$ : L293	$\pm 1$ A
Continuous output current, $I_O$ : L293D	$\pm 600$ mA
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): DWP package	TBD $^{\circ}$ C/W
N package	67 $^{\circ}$ C/W
NE package	TBD $^{\circ}$ C/W
Maximum junction temperature, $T_J$	150 $^{\circ}$ C
Storage temperature range, $T_{stg}$	-65 $^{\circ}$ C to 150 $^{\circ}$ C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the network ground terminal.

2. Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150 $^{\circ}$ C can affect reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

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## recommended operating conditions

		MIN	MAX	UNIT
Supply voltage	$V_{CC1}$	4.5	7	V
	$V_{CC2}$	$V_{CC1}$	36	
$V_{IH}$ High-level input voltage	$V_{CC1} \leq 7\text{ V}$	2.3	$V_{CC1}$	V
	$V_{CC1} \geq 7\text{ V}$	2.3	7	V
$V_{IL}$ Low-level output voltage		-0.3†	1.5	V
$T_A$ Operating free-air temperature		0	70	°C

† The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.

## electrical characteristics, $V_{CC1} = 5\text{ V}$ , $V_{CC2} = 24\text{ V}$ , $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{OH}$ High-level output voltage		L293: $I_{OH} = -1\text{ A}$ L293D: $I_{OH} = -0.6\text{ A}$		$V_{CC2} - 1.8$	$V_{CC2} - 1.4$		V
$V_{OL}$ Low-level output voltage		L293: $I_{OL} = 1\text{ A}$ L293D: $I_{OL} = 0.6\text{ A}$			1.2	1.8	V
$V_{OKH}$ High-level output clamp voltage		L293D: $I_{OK} = -0.6\text{ A}$			$V_{CC2} + 1.3$		V
$V_{OKL}$ Low-level output clamp voltage		L293D: $I_{OK} = 0.6\text{ A}$			1.3		V
$I_{IH}$ High-level input current	A	$V_I = 7\text{ V}$			0.2	100	$\mu\text{A}$
	EN				0.2	10	
$I_{IL}$ Low-level input current	A	$V_I = 0$			-3	-10	$\mu\text{A}$
	EN				-2	-100	
$I_{CC1}$ Logic supply current	$I_O = 0$	All outputs at high level			13	22	mA
		All outputs at low level			35	60	
		All outputs at high impedance			8	24	
$I_{CC2}$ Output supply current	$I_O = 0$	All outputs at high level			14	24	mA
		All outputs at low level			2	6	
		All outputs at high impedance			2	4	

## switching characteristics, $V_{CC1} = 5\text{ V}$ , $V_{CC2} = 24\text{ V}$ , $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	L293NE, L293DNE			UNIT
			MIN	TYP	MAX	
$t_{PLH}$ Propagation delay time, low-to-high-level output from A input		$C_L = 30\text{ pF}$ , See Figure 1		800		ns
$t_{PHL}$ Propagation delay time, high-to-low-level output from A input				400		ns
$t_{TLH}$ Transition time, low-to-high-level output				300		ns
$t_{THL}$ Transition time, high-to-low-level output				300		ns

## switching characteristics, $V_{CC1} = 5\text{ V}$ , $V_{CC2} = 24\text{ V}$ , $T_A = 25^\circ\text{C}$

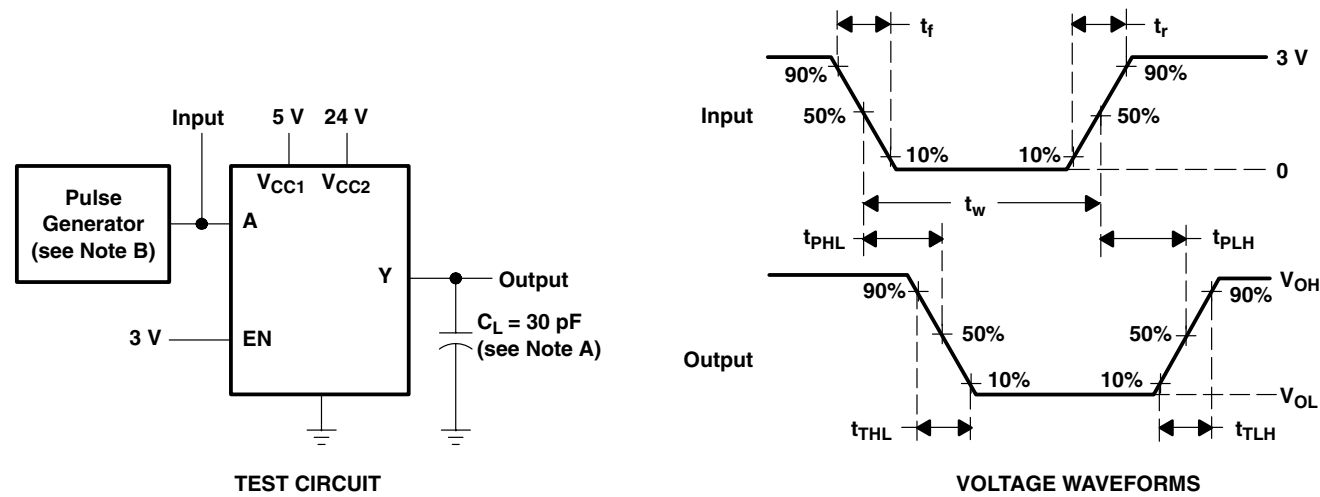
PARAMETER		TEST CONDITIONS	L293DWP, L293N L293DN			UNIT
			MIN	TYP	MAX	
$t_{PLH}$ Propagation delay time, low-to-high-level output from A input		$C_L = 30\text{ pF}$ , See Figure 1		750		ns
$t_{PHL}$ Propagation delay time, high-to-low-level output from A input				200		ns
$t_{TLH}$ Transition time, low-to-high-level output				100		ns
$t_{THL}$ Transition time, high-to-low-level output				350		ns



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PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics:  $t_r \leq 10$  ns,  $t_f \leq 10$  ns,  $t_w = 10$   $\mu$ s, PRR = 5 kHz,  $Z_O = 50$   $\Omega$ .

Figure 1. Test Circuit and Voltage Waveforms

APPLICATION INFORMATION

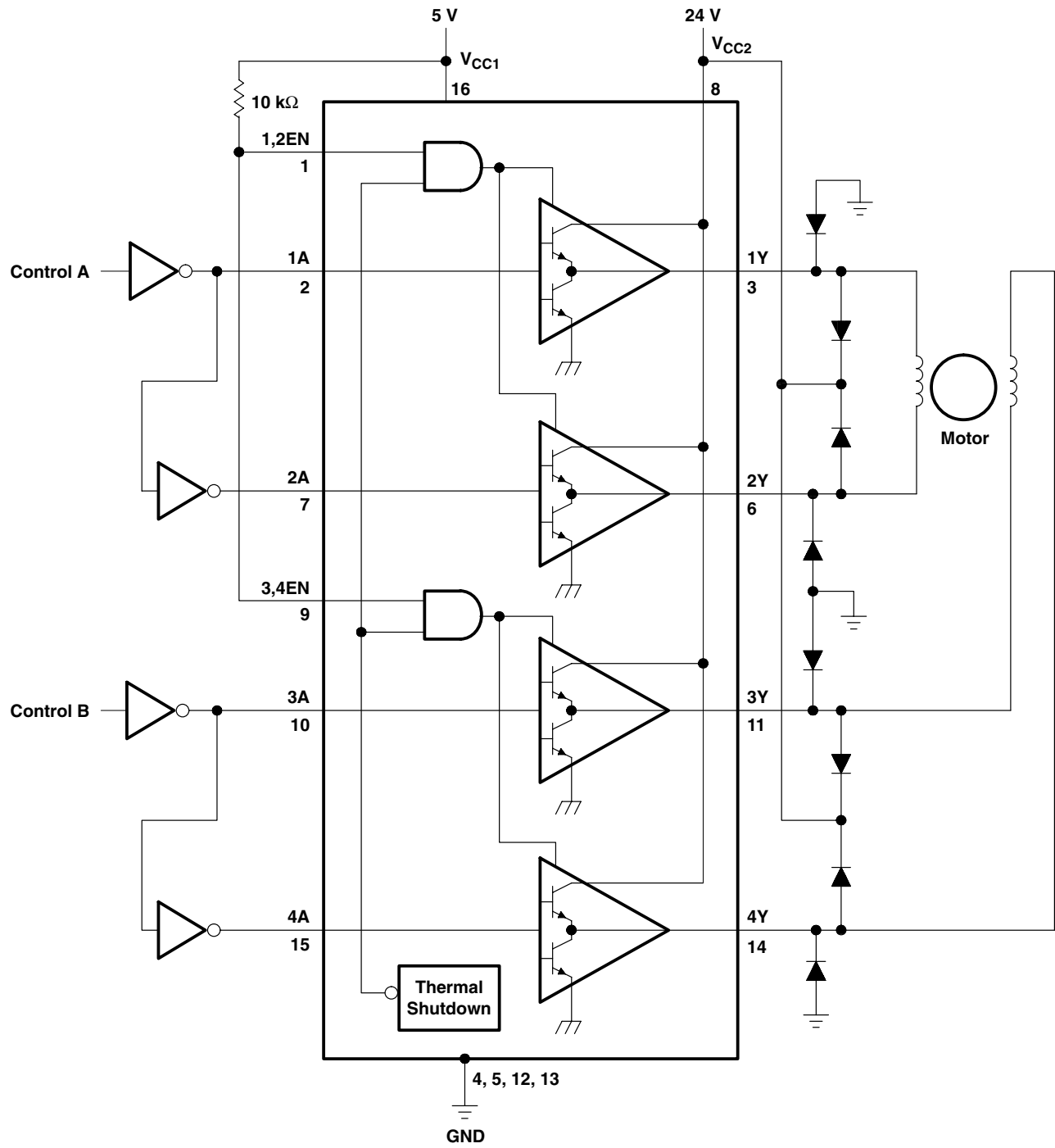


Figure 2. Two-Phase Motor Driver (L293)

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## APPLICATION INFORMATION

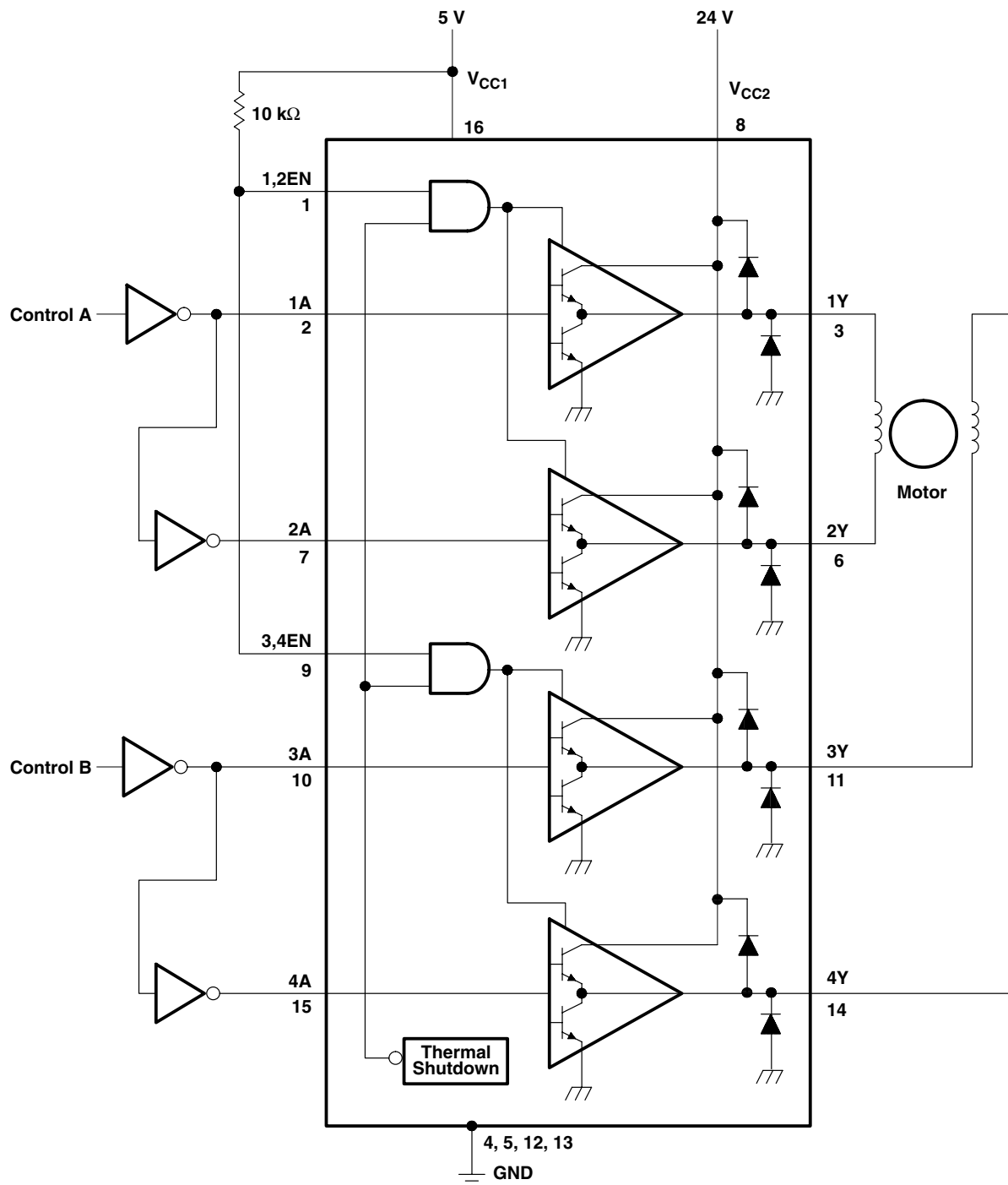


Figure 3. Two-Phase Motor Driver (L293D)



APPLICATION INFORMATION

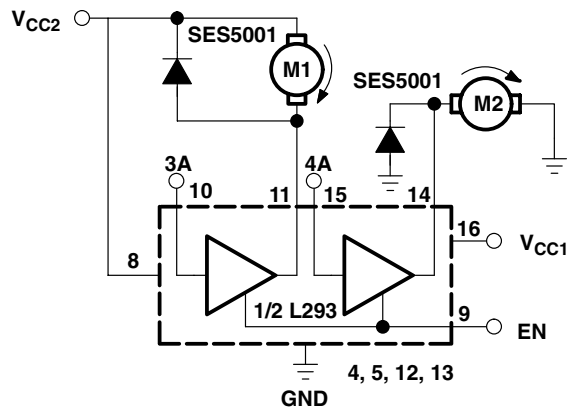


Figure 4. DC Motor Controls  
(connections to ground and to  
supply voltage)

EN	3A	M1	4A	M2
H	H	Fast motor stop	H	Run
H	L	Run	L	Fast motor stop
L	X	Free-running motor stop	X	Free-running motor stop

L = low, H = high, X = don't care

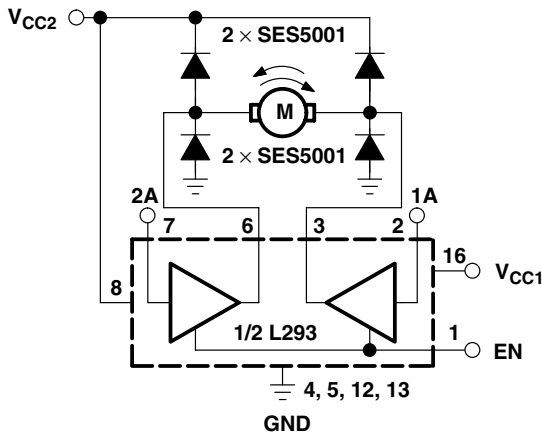


Figure 5. Bidirectional DC Motor Control

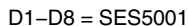
EN	1A	2A	FUNCTION
H	L	H	Turn right
H	H	L	Turn left
H	L	L	Fast motor stop
H	H	H	Fast motor stop
L	X	X	Fast motor stop

L = low, H = high, X = don't care

## L293, L293D

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## APPLICATION INFORMATION



### Figure 6. Bipolar Stepping-Motor Control

## mounting instructions

The Rthj-amp of the L293 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board or to an external heat sink.

Figure 9 shows the maximum package power  $P_{TOT}$  and the  $\theta_{JA}$  as a function of the side  $\ell$  of two equal square copper areas having a thickness of  $35\text{ }\mu\text{m}$  (see Figure 7). In addition, an external heat sink can be used (see Figure 8).

During soldering, the pin temperature must not exceed 260°C, and the soldering time must not exceed 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

## APPLICATION INFORMATION

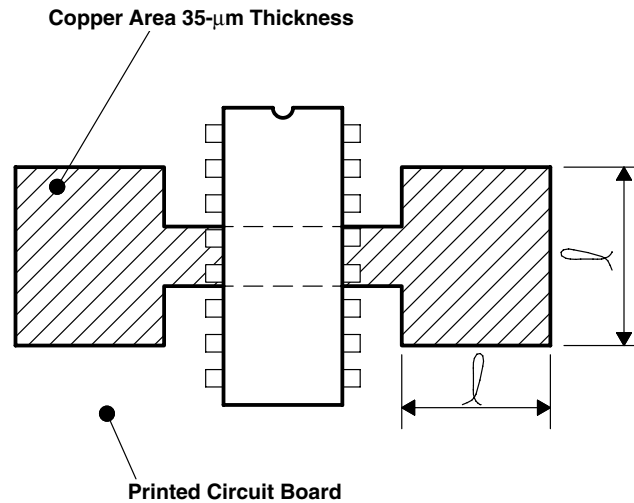


Figure 7. Example of Printed Circuit Board Copper Area (used as heat sink)

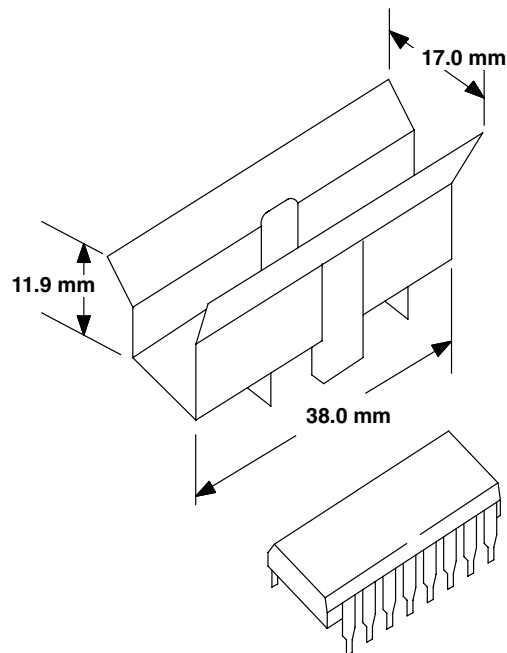


Figure 8. External Heat Sink Mounting Example  
( $\theta_{JA} = 25^{\circ}\text{C/W}$ )

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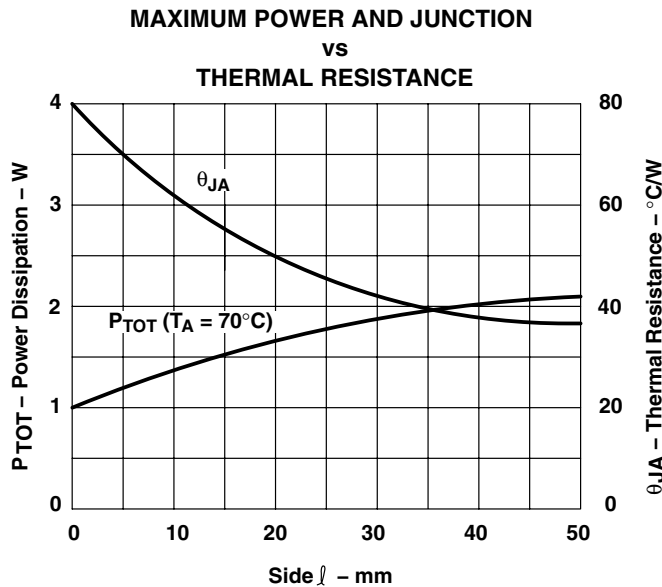


Figure 9

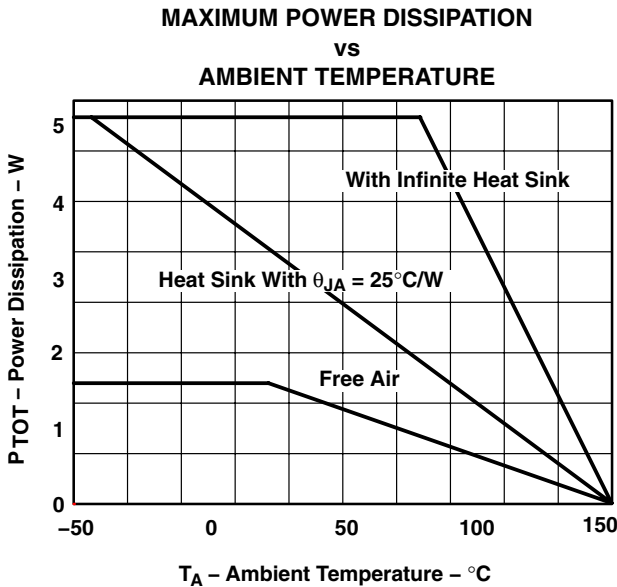


Figure 10

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
L293DNE	ACTIVE	PDIP	NE	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	L293DNE	<a href="#">Samples</a>
L293DNEE4	ACTIVE	PDIP	NE	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	L293DNE	<a href="#">Samples</a>
L293NE	ACTIVE	PDIP	NE	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	L293NE	<a href="#">Samples</a>
L293NEE4	ACTIVE	PDIP	NE	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	L293NE	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

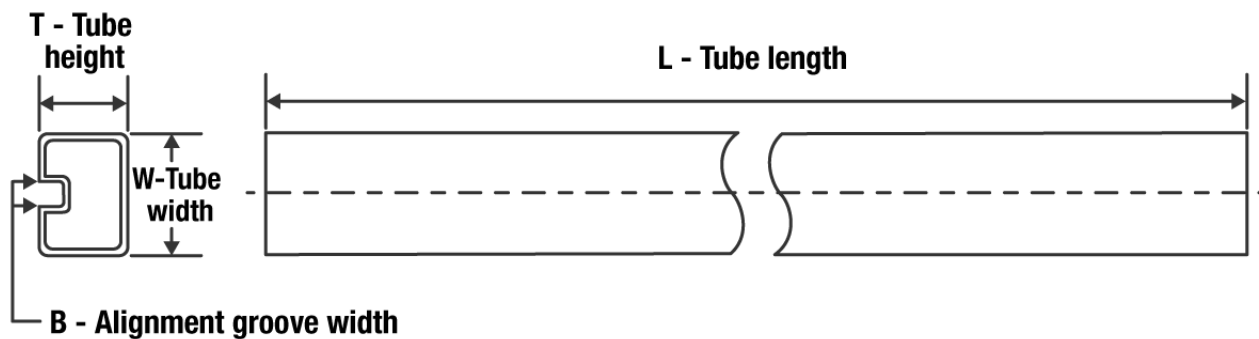
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
L293DNE	NE	PDIP	16	25	506	13.97	11230	4.32
L293DNEE4	NE	PDIP	16	25	506	13.97	11230	4.32
L293NE	NE	PDIP	16	25	506	13.97	11230	4.32
L293NEE4	NE	PDIP	16	25	506	13.97	11230	4.32

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